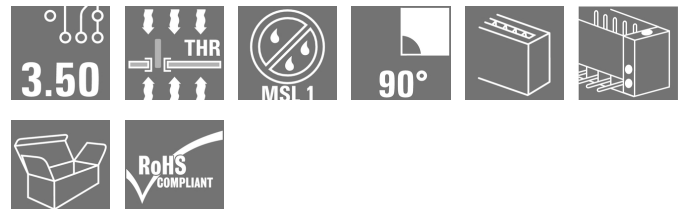


SL-SMT 3.50/10/90RF 1.5SN BK BX**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com**Product image**

Similar to illustration

High-temperature-resistant male header, 3.50 mm pitch.

- **Plugging direction parallel (90°), straight 180° or angled (135°) to PCB**
- **Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)**
- **Optimised for the SMT process**
- **Pin length 3.2 mm universal for all soldering methods**
- **Pin length 1.5 mm optimised for reflow soldering methods**
- **Packed either in a box (BX) or tape-on-reel (RL)**
- **Male header can be coded**

General ordering data

Version	PCB plug-in connector, male header, Clip-on flange, THT/THR solder connection, 3.50 mm, Number of poles: 10, 90°, Solder pin length (l): 1.5 mm, tinned, black, Box
Order No.	1060780000
Type	SL-SMT 3.50/10/90RF 1.5SN BK BX
GTIN (EAN)	4032248810246
Qty.	50 pc(s).
Product data	IEC: 320 V / 15 A UL: 300 V / 10 A
Packaging	Box

SL-SMT 3.50/10/90RF 1.5SN BK BX**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Technical data**Dimensions and weights**

Depth	11.1 mm	Depth (inches)	0.437 inch
Height	9 mm	Height (inches)	0.354 inch
Height of lowest version	7.5 mm	Width	41.86 mm
Width (inches)	1.648 inch	Net weight	3.068 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 3.50	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.5 mm
Pitch in inches (P)	0.138 inch	Outgoing elbow	90°
Number of poles	10	Number of solder pins per pole	1
Solder pin length (l)	1.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0.03 mm
Solder eyelet hole diameter (D)	1.4 mm	Solder eyelet hole diameter tolerance (D)+	0.1 mm
Outside diameter of solder pad	2.3 mm	Template aperture diameter	2.1 mm
L1 in mm	31.5 mm	L1 in inches	1.24 inch
Number of rows	1	Pin series quantity	1
Touch-safe protection acc. to DIN VDE 57 106	Safe from back-of-hand touch	Touch-safe protection acc. to DIN VDE 0470	IP 10
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging force/pole, max.	6 N	Pulling force/pole, max.	6 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIla
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Copper alloy
Contact surface	tinned	Layer structure of solder connection	2...3 µm Ni / 5...7 µm Sn
Layer structure of plug contact	2...3 µm Ni / 5...7 µm Sn	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	15 A
Rated current, max. number of poles (Tu=20°C)	12 A	Rated current, min. number of poles (Tu=40°C)	13 A
Rated current, max. number of poles (Tu=40°C)	10 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 100 A

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	10 A	Rated current (Use group D / CSA)	10 A

SL-SMT 3.50/10/90RF 1.5SN BK BX**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com**Technical data****Packing**

Packaging	Box	VPE length	97 mm
VPE width	66 mm	VPE height	54 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet $D = 1.4 \pm 0.1 \text{ mm}$ • Solder eyelet diameter $D = 1.5 \pm 0.1 \text{ mm}$, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals



ROHS	Conform
UL File Number Search	UL Website
Certificate No. (UR)	E60693

SL-SMT 3.50/10/90RF 1.5SN BK BX

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

Technical data

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN
	MB SMT EN
	FL DRIVES DE
	MB DEVICE MANUF. EN
	FL BUILDING SAFETY EN
	FL APPL LED LIGHTING EN
	FL INDUSTR.CONTROLS EN
	FL MACHINE SAFETY EN
	FL HEATING ELECTR EN
	FL APPL INVERTER EN
	FL_BASE_STATION_EN
	FL ELEVATOR EN
	FL POWER SUPPLY EN
	FL 72H SAMPLE SER EN
White paper surface mount technology	PO OMNIMATE EN
	PO OMNIMATE EN
Download Whitepaper	

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

Drawings

Technical drawing of a multi-layered material cross-section. The drawing shows a cross-section with various layers and dimensions. Key dimensions and labels include:

- L_{PPP} : Total length of the top layer.
- $A0$: Width of the top layer.
- $L01 (PPP)$: Length of the first internal layer.
- $L02 (PPP)$: Length of the second internal layer.
- $P1$: Thickness of the first internal layer.
- $B0$: Total thickness of the material.
- $BPPP$: Thickness of the top layer.
- $K0$: Thickness of the bottom layer.
- $T2$: Thickness of the bottom layer.
- E : Thickness of the internal layers.
- W : Width of the internal layers.
- ΦD_{max} : Maximum diameter of the internal layers.
- DIRECTION OF UNREELING**: Indicated by an arrow pointing to the right.

Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.